

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#4/A
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Murphy

Applicants: B. S. Beaman et al. Date: August 25, 1999
Serial No.: Prior Group Art Unit: 3729
Filed: Herewith Prior Examiner: C. Arbes
For: HIGH DENSITY INTEGRATED CIRCUIT APPARATUS,
TEST PROBE AND METHODS OF USE THEREOF

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

IN THE CLAIMS

Cancel claims 1-28.

Add Claims 29-52.

29. (Added) A method of probing an electronic device by contacting the electronic device with a plurality of flexible contact elements, the method comprising the steps of:

providing a first substrate corresponding to an area of the electronic device to be probed, said substrate having a front surface; and

mounting and connecting a second substrate to the front surface of the first substrate, said second substrate having a plurality of flexible contact elements extending from a surface thereof; and

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